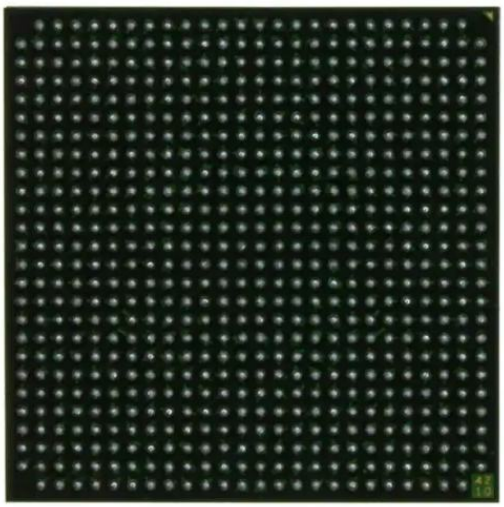

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Details	
Product Status	Obsolete
Number of LABs/CLBs	352
Number of Logic Elements/Cells	3168
Total RAM Bits	221184
Number of I/O	204
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FCBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp2-6ff672c

Table 9: **Supported Differential Signal I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Output V_{OD}
LDT_25	2.5	N/R	N/R	0.500 – 0.740
LVDS_25	2.5	N/R	N/R	0.247 – 0.454
LVDSEXT_25	2.5	N/R	N/R	0.440 – 0.820
BLVDS_25	2.5	N/R	N/R	0.250 – 0.450
ULVDS_25	2.5	N/R	N/R	0.500 – 0.740
LVPECL_25	2.5	N/R	N/R	0.345 – 1.185
LDT_25_DT(1)	2.5	2.5	N/R	0.500 – 0.740
LVDS_25_DT(1)	2.5	2.5	N/R	0.247 – 0.454
LVDSEXT_25_DT(1)	2.5	2.5	N/R	0.330 – 0.700
ULVDS_25_DT(1)	2.5	2.5	N/R	0.500 – 0.740

Notes:
1. These standards support on-chip 100Ω termination.
2. N/R = no requirement.

Table 10: **Supported DCI I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Termination Type
LVDCI_33(1)	3.3	3.3	N/R	Series
LVDCI_25	2.5	2.5	N/R	Series
LVDCI_DV2_25	2.5	2.5	N/R	Series
LVDCI_18	1.8	1.8	N/R	Series
LVDCI_DV2_18	1.8	1.8	N/R	Series
LVDCI_15	1.5	1.5	N/R	Series
LVDCI_DV2_15	1.5	1.5	N/R	Series
GTL_DCI	1.2	1.2	0.8	Single
GTLP_DCI	1.5	1.5	1.0	Single
HSTL_I_DCI	1.5	1.5	0.75	Split
HSTL_II_DCI	1.5	1.5	0.75	Split
HSTL_III_DCI	1.5	1.5	0.9	Single
HSTL_IV_DCI	1.5	1.5	0.9	Single
HSTL_I_DCI_18	1.8	1.8	0.9	Split
HSTL_II_DCI_18	1.8	1.8	0.9	Split
HSTL_III_DCI_18	1.8	1.8	1.1	Single
HSTL_IV_DCI_18	1.8	1.8	1.1	Single
SSTL2_I_DCI(2)	2.5	2.5	1.25	Split
SSTL2_II_DCI(2)	2.5	2.5	1.25	Split
SSTL18_I_DCI (3)	1.8	1.8	0.9	Split
SSTL18_II_DCI	1.8	1.8	0.9	Split

Table 10: **Supported DCI I/O Standards *(Continued)***

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Termination Type
LVDS_25_DCI	2.5	2.5	N/R	Split
LVDSEXT_25_DCI	2.5	2.5	N/R	Split

Notes:
1. LVDCI_XX is LVCMOS output controlled impedance buffers, matching all or half of the reference resistors.
2. These are SSTL compatible.
3. SSTL18_I is not a JEDEC-supported standard.
4. N/R = no requirement.

Logic Resources

IOB blocks include six storage elements, as shown in Figure 19.

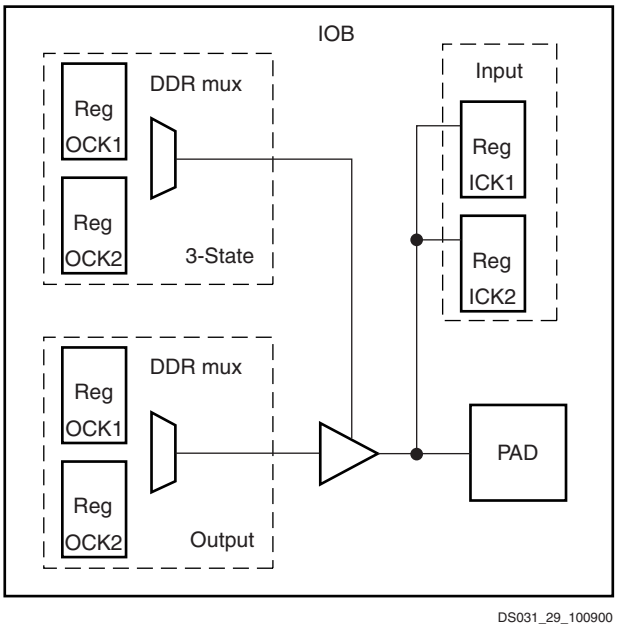

Figure 19: **Virtex-II Pro IOB Block**

Each storage element can be configured either as an edge-triggered D-type flip-flop or as a level-sensitive latch. On the input, output, and 3-state path, one or two DDR registers can be used.

Double data rate is directly accomplished by the two registers on each path, clocked by the rising edges (or falling edges) from two different clock nets. The two clock signals are generated by the DCM and must be 180 degrees out of phase, as shown in Figure 20. There are two input, output, and 3-state data signals, each being alternately clocked out.

LVDS DC Specifications (LVDS_25)

Table 8: **LVDS DC Specifications**

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.38	2.5	2.63	V
Output High Voltage for Q and $\overline{Q}$	V_{OH}	R_T = 100 Ω across Q and $\overline{Q}$ signals			1.602	V
Output Low Voltage for Q and $\overline{Q}$	V_{OL}	R_T = 100 Ω across Q and $\overline{Q}$ signals	0.898			V
Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{ODIFF}	R_T = 100 Ω across Q and $\overline{Q}$ signals	247	350	454	mV
Output Common-Mode Voltage	V_{OCM}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.125	1.250	1.375	V
Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25V	100	350	600	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ±350 mV	0.3	1.2	2.2	V

Extended LVDS DC Specifications (LVDSEXT_25)

Table 9: **Extended LVDS DC Specifications**

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.38	2.5	2.63	V
Output High Voltage for Q and $\overline{Q}$	V_{OH}	R_T = 100 Ω across Q and $\overline{Q}$ signals			1.785	V
Output Low Voltage for Q and $\overline{Q}$	V_{OL}	R_T = 100 Ω across Q and $\overline{Q}$ signals	0.715			V
Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{ODIFF}	R_T = 100 Ω across Q and $\overline{Q}$ signals	440		820	mV
Output Common-Mode Voltage	V_{OCM}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.125	1.250	1.375	V
Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25V	100		1000	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ±350 mV	0.3	1.2	2.2	V

LVPECL DC Specifications (LVPECL_25)

These values are valid when driving a 100 Ω differential load only, i.e., a 100 Ω resistor between the two receiver pins. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. Table 10 summarizes the DC output specifications of LVPECL. For more information on using LVPECL, see the *Virtex-II Pro Platform FPGA User Guide*.

Table 10: **LVPECL DC Specifications**

DC Parameter	V_{CCO} = 2.375V		V_{CCO} = 2.5V		V_{CCO} = 2.625V		Units
	Min	Max	Min	Max	Min	Max	
V_{OH}	1.35	1.495	1.475	1.62	1.6	1.745	V
V_{OL}	0.565	0.755	0.69	0.88	0.815	1.005	V
V_{IH}	0.8	2.0	0.8	2.0	0.8	2.0	V
V_{IL}	0.5	1.7	0.5	1.7	0.5	1.7	V
Differential Input Voltage	0.100	1.5	0.100	1.5	0.100	1.5	V

Table 26: **RocketIO X Transmitter Switching Characteristics**(1)

Description	Symbol	Conditions	BREFCLK Frequency	Min	Typ	Max	Units
Serial data rate	F_{GTX}			2.488		6.25	Gb/s
Serial data output total jitter (p-p)(3)	T_{TJ}	2.488 Gb/s			0.15	0.20	UI(2)
		3.125 Gb/s			0.14	0.19	UI
		4.25 Gb/s			0.39	0.48	UI
		6.25 Gb/s			0.42	0.54	UI
Serial data output deterministic jitter (p-p)(3)	T_{DJ}	2.488 Gb/s	155.52 MHz		0.03	0.17	UI
		3.125 Gb/s	156.25 MHz		0.03	0.17	UI
		4.25 Gb/s	212.5 MHz		0.14	0.26	UI
		6.25 Gb/s	312.5 MHz		0.17	0.35	UI
Serial data output random jitter (p-p)(3,4)	T_{RJ}	2.488 Gb/s	155.52 MHz		0.12	0.18	UI
		3.125 Gb/s	156.25 MHz		0.12	0.20	UI
		4.25 Gb/s	212.5 MHz		0.25	0.39	UI
		6.25 Gb/s	312.5 MHz		0.25	0.39	UI
TX rise time	T_{RTX}	20% – 80% @ 2.500 Gb/s			60		ps
TX fall time	T_{FTX}				60		ps
Transmit latency(5)	T_{TXLAT}				14	19	TXUSRCLK cycles
TXUSRCLK duty cycle	T_{TXDC}			45	50	55	%
TXUSRCLK2 duty cycle	T_{TX2DC}			45	50	55	%

Notes:
1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Total Jitter $T_{TJ} = T_{DJ} + T_{RJ}$
4. T_{RJ} specifications are *wideband* and include low-frequency jitter components (also referred to as *wander*).T_{RJ} specified is peak-to-peak, estimated at BER=10^{-12} using the Bathtub Method.
5. Transmit latency delay TXDATA to TXP/TXN. Refer to ***RocketIO X Transceiver User Guide*** for more information on calculating latency.

IOB Input Switching Characteristics Standard Adjustments

Table 36 gives all standard-specific data input delay adjustments.

Table 36: **IOB Input Switching Characteristics Standard Adjustments**

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
LVTTL (Low-Voltage Transistor-Transistor Logic)	LVTTL	T_{ILVTTL}	0.07	0.08	0.09	ns
LVCMOS (Low-Voltage CMOS), 3.3V	LVCMOS33	$T_{ILVCMOS33}$	0.04	0.05	0.05	ns
LVCMOS, 2.5V	LVCMOS25	$T_{ILVCMOS25}$	0.00	0.00	0.00	ns
LVCMOS, 1.8V	LVCMOS18	$T_{ILVCMOS18}$	0.29	0.33	0.36	ns
LVCMOS, 1.5V	LVCMOS15	$T_{ILVCMOS15}$	0.36	0.41	0.45	ns
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	T_{ILVDS_25}	0.31	0.36	0.40	ns
LVDSEXT (LVDS Extended Mode), 2.5V	LVDSEXT_25	$T_{ILVDSEXT\_25}$	0.33	0.37	0.41	ns
ULVDS (Ultra LVDS), 2.5V	ULVDS_25	T_{IULVDS_25}	0.31	0.36	0.40	ns
BLVDS (Bus LVDS), 2.5V	BLVDS_25	T_{IBLVDS_25}	0.00	0.00	0.00	ns
LDT (HyperTransport), 2.5V	LDT_25	T_{ILDT_25}	0.31	0.36	0.40	ns
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V	LVPECL_25	$T_{ILVPECL\_25}$	0.69	0.80	0.88	ns
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3	T_{IPCI33_3}	0.14	0.16	0.18	ns
PCI, 66 MHz, 3.3V	PCI66_3	T_{IPCI66_3}	0.15	0.17	0.19	ns
PCI-X, 133 MHz, 3.3V	PCIX	T_{IPCIX}	0.12	0.13	0.15	ns
GTL (Gunning Transceiver Logic)	GTL	T_{IGTL}	0.59	0.68	0.74	ns
GTL Plus	GTLP	T_{IGTLP}	0.63	0.72	0.79	ns
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	T_{IHSTL_I}	0.59	0.68	0.75	ns
HSTL, Class II	HSTL_II	T_{IHSTL_II}	0.59	0.68	0.75	ns
HSTL, Class III	HSTL_III	T_{IHSTL_III}	0.57	0.66	0.72	ns
HSTL, Class IV	HSTL_IV	T_{IHSTL_IV}	0.58	0.67	0.74	ns
HSTL, Class I, 1.8V	HSTL_I_18	$T_{IHSTL\_I\_18}$	0.57	0.65	0.72	ns
HSTL, Class II, 1.8V	HSTL_II_18	$T_{IHSTL\_II\_18}$	0.55	0.63	0.69	ns
HSTL, Class III, 1.8V	HSTL_III_18	$T_{IHSTL\_III\_18}$	0.56	0.64	0.70	ns
HSTL, Class IV, 1.8V	HSTL_IV_18	$T_{IHSTL\_IV\_18}$	0.57	0.65	0.71	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	$T_{ISSTL18\_I}$	0.62	0.72	0.79	ns
SSTL, Class II, 1.8V	SSTL18_II	$T_{ISSTL18\_II}$	0.64	0.73	0.81	ns
SSTL, Class I, 2.5V	SSTL2_I	T_{ISSTL2_I}	0.62	0.72	0.79	ns
SSTL, Class II, 2.5V	SSTL2_II	T_{ISSTL2_II}	0.64	0.73	0.81	ns
LVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	T_{ILVDCI_33}	–0.05	–0.05	–0.06	ns
LVDCI, 2.5V	LVDCI_25	T_{ILVDCI_25}	0.00	0.00	0.00	ns
LVDCI, 1.8V	LVDCI_18	T_{ILVDCI_18}	0.07	0.09	0.09	ns
LVDCI, 1.5V	LVDCI_15	T_{ILVDCI_15}	0.13	0.15	0.17	ns
LVDCI, 2.5V, Half-Impedance	LVDCI_DV2_25	$T_{ILVDCI\_DV2\_25}$	0.00	0.00	0.00	ns
LVDCI, 1.8V, Half-Impedance	LVDCI_DV2_18	$T_{ILVDCI\_DV2\_18}$	0.07	0.09	0.09	ns
LVDCI, 1.5V, Half-Impedance	LVDCI_DV2_15	$T_{ILVDCI\_DV2\_15}$	0.13	0.15	0.17	ns
HSLVDCI (High-Speed Low-Voltage DCI), 1.5V	HSLVDCI_15	$T_{IHSLVDCI\_15}$	0.59	0.68	0.75	ns

Master/Slave Serial Mode Parameters

Clock timing for Slave Serial configuration programming is shown in Figure 8, with Master Serial clock timing shown in Figure 9. Programming parameters for both Slave and Master modes are given in Table 50.

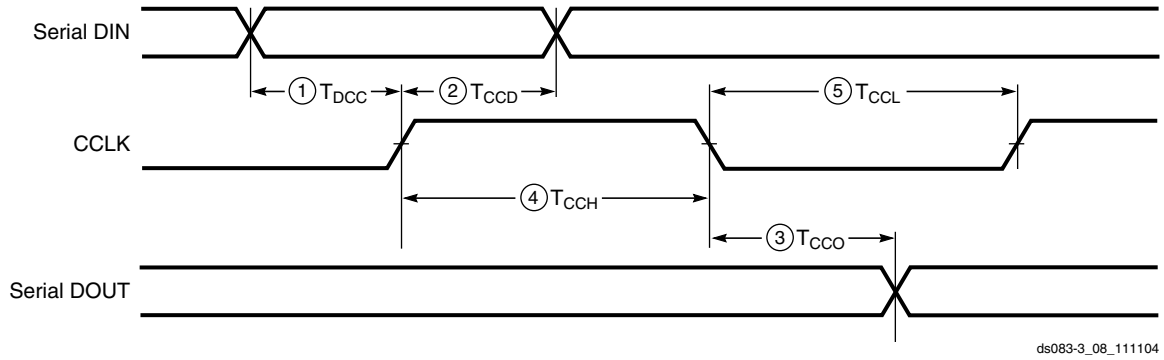

Figure 8: **Slave Serial Mode Timing Sequence**

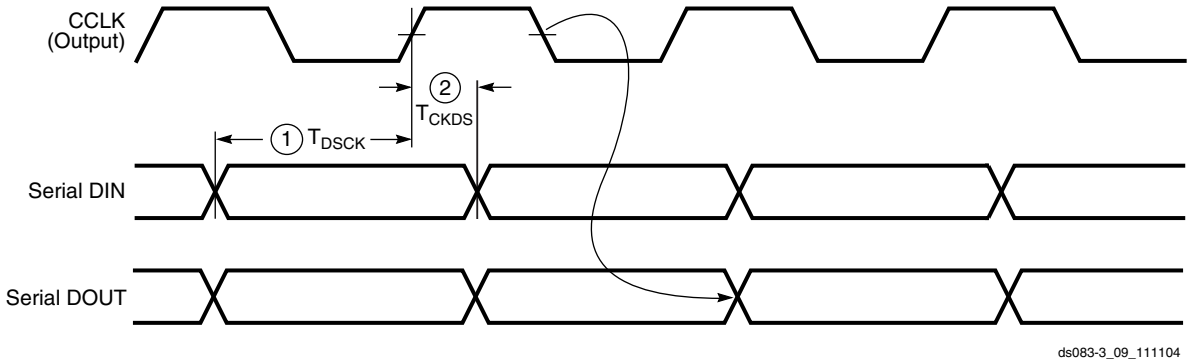

Figure 9: **Master Serial Mode Timing Sequence**

Table 50: **Master/Slave Serial Mode Timing Characteristics**

	Description	Figure References	Symbol	Value	Units
CCLK	DIN setup/hold, slave mode (Figure 8)	1/2	T_{DCC}/T_{CCD}	5.0/0.0	ns, min
	DIN setup/hold, master mode (Figure 9)	1/2	T_{DSCK}/T_{CKDS}	5.0/0.0	ns, min
	DOUT	3	T_{CCO}	12.0	ns, max
	High time	4	T_{CCH}	5.0	ns, min
	Low time	5	T_{CCL}	5.0	ns, min
	Maximum start-up frequency		$F_{CC\_STARTUP}$	50	MHz, max
	Maximum frequency		F_{CC_SERIAL}	66(1)	MHz, max
	Frequency tolerance, master mode with respect to nominal			+45% –30%	

Notes:
1. If no provision is made in the design to adjust the frequency of CCLK, F_{CC_SERIAL} should not exceed $F_{CC\_STARTUP}$.

Output Clock Jitter

Table 59: **Output Clock Jitter**

Description	Symbol	Constraints	Speed Grade			Units
			–7	–6	–5	
Clock Synthesis Period Jitter						
CLK0	CLKOUT_PER_JITT_0		±100	±100	±100	ps
CLK90	CLKOUT_PER_JITT_90		±150	±150	±150	ps
CLK180	CLKOUT_PER_JITT_180		±150	±150	±150	ps
CLK270	CLKOUT_PER_JITT_270		±150	±150	±150	ps
CLK2X, CLK2X180	CLKOUT_PER_JITT_2X		±200	±200	±200	ps
CLKDV (integer division)	CLKOUT_PER_JITT_DV1		±150	±150	±150	ps
CLKDV (non-integer division)	CLKOUT_PER_JITT_DV2		±300	±300	±300	ps
CLKFX, CLKFX180	CLKOUT_PER_JITT_FX		Note (1)	Note (1)	Note (1)	ps

Notes:
1. Use the **Jitter Calculator** on the Xilinx website (http://www.xilinx.com/applications/web_ds_v2/jitter_calc.htm) for CLKFX and CLKFX180 output jitter.

Output Clock Phase Alignment

Table 60: **Output Clock Phase Alignment**

Description	Symbol	Constraints	Speed Grade			Units
			–7	–6	–5	
Phase Offset Between CLKIN and CLKFB						
CLKIN/CLKFB	CLKIN_CLKFB_PHASE		±50	±50	±50	ps
Phase Offset Between Any DCM Outputs						
All CLK* outputs	CLKOUT_PHASE		±140	±140	±140	ps
Duty Cycle Precision						
DLL outputs(1)	CLKOUT_DUTY_CYCLE_DLL(2)		±150	±150	±150	ps
CLKFX outputs	CLKOUT_DUTY_CYCLE_FX		±100	±100	±100	ps

Notes:
1. “DLL outputs” is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. CLKOUT_DUTY_CYCLE_DLL applies to the 1X clock outputs (CLK0, CLK90, CLK180, and CLK270) only if DUTY_CYCLE_CORRECTION = TRUE.
3. Specification also applies to PSCLK.

Table 4: **Virtex-II Pro Pin Definitions *(Continued)***

Pin Name	Direction	Description
GCLKx (S/P)	Input/Output	These are clock input pins that connect to Global Clock Buffers. These pins become regular user I/Os when not needed for clocks. These pins can be used to clock the RocketIO transceiver. See the **RocketIO Transceiver User Guide** for design guidelines and BREFCLK-specific pins, by device.
VRP	Input	This pin is for the DCI voltage reference resistor of P transistor (per bank).
VRN	Input	This pin is for the DCI voltage reference resistor of N transistor (per bank).
V_{REF}	Input	These are input threshold voltage pins. They become user I/Os when an external threshold voltage is not needed (per bank).
Dedicated Pins:(1)		
CCLK	Input/Output	Configuration clock. Output in Master mode or Input in Slave mode.
PROG_B	Input	Active Low asynchronous reset to configuration logic. This pin has a permanent weak pull-up resistor.
DONE	Input/Output	DONE is a bidirectional signal with an optional internal pull-up resistor. As an output, this pin indicates completion of the configuration process. As an input, a Low level on DONE can be configured to delay the start-up sequence.
M2, M1, M0	Input	Configuration mode selection. Pin is biased by V_{CCAUX} (must be 2.5V). These pins should not connect to 3.3V unless 100Ω series resistors are used. The mode pins are not to be toggled (changed) while in operation during and after configuration.
HSWAP_EN	Input	Enable I/O pull-ups during configuration.
TCK	Input	Boundary Scan Clock. This pin is 3.3V compatible.
TDI	Input	Boundary Scan Data Input. This pin is 3.3V compatible.
TDO	Output (open-drain)	Boundary Scan Data Output. Pin is open-drain and can be pulled up to 3.3V. It is recommended that the external pull-up be greater than 200Ω. There is no internal pull-up.
TMS	Input	Boundary Scan Mode Select. This pin is 3.3V compatible.
PWRDWN_B	Input *(unsupported)*	Active Low power-down pin (unsupported). *Driving this pin Low can adversely affect device operation and configuration.* PWRDWN_B is internally pulled High, which is its default state. It does not require an external pull-up.
Other Pins:		
DXN, DXP	N/A	Temperature-sensing diode pins (Anode: DXP, Cathode: DXN).
V_{BATT}	Input	Decryptor key memory backup supply. (Connect to V_{CCAUX} or GND if battery not used.)
RSVD	N/A	Reserved pin - do not connect.
V_{CCO}	Input	Power-supply pins for the output drivers (per bank).
V_{CCAUX}	Input	Power-supply pins for auxiliary circuits.
V_{CCINT}	Input	Power-supply pins for the internal core logic.
GND	Input	Ground.
AVCCAUXRX#	Input	Analog power supply for receive circuitry of the RocketIO MGT (2.5V).
AVCCAUXTX#	Input	Analog power supply for transmit circuitry of the RocketIO MGT (2.5V).
BREFCLKN, BREFCLKP(2)	Input	Differential clock input that clocks the RocketIO X MGTs populating the same side of the chip (top or bottom). Can also drive DCMs for RocketIO X MGT use.

Table 5: **FG256/FGG256 — XC2VP2 and XC2VP4**

Bank	Pin Description	Pin Number
7	IO_L85N_7	G2
7	IO_L06P_7	G3
7	IO_L06N_7	G4
7	IO_L04P_7	F1
7	IO_L04N_7/VREF_7	F2
7	IO_L03P_7	F3
7	IO_L03N_7	F4
7	IO_L02P_7	F5
7	IO_L02N_7	E4
7	IO_L01P_7/VRN_7	E2
7	IO_L01N_7/VRP_7	E3
0	VCCO_0	F8
0	VCCO_0	F7
0	VCCO_0	E8
1	VCCO_1	F9
1	VCCO_1	F10
1	VCCO_1	E9
2	VCCO_2	H12
2	VCCO_2	H11
2	VCCO_2	G11
3	VCCO_3	K11
3	VCCO_3	J12
3	VCCO_3	J11
4	VCCO_4	M9
4	VCCO_4	L9
4	VCCO_4	L10
5	VCCO_5	M8
5	VCCO_5	L8
5	VCCO_5	L7
6	VCCO_6	K6
6	VCCO_6	J6
6	VCCO_6	J5
7	VCCO_7	H6
7	VCCO_7	H5

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	VCCO_7	K7			
7	VCCO_7	J7			
7	VCCO_7	H6			
7	VCCO_7	G6			
N/A	CCLK	W20			
N/A	PROG_B	B1			
N/A	DONE	Y18			
N/A	M0	Y4			
N/A	M1	W3			
N/A	M2	Y5			
N/A	TCK	B22			
N/A	TDI	D3			
N/A	TDO	D20			
N/A	TMS	A21			
N/A	PWRDWN_B	Y19			
N/A	HSWAP_EN	A2			
N/A	RSVD	C18			
N/A	VBATT	C19			
N/A	DXP	C4			
N/A	DXN	C5			
N/A	AVCCAUXTX4	B4	NC	NC	
N/A	VTTXPAD4	B3	NC	NC	
N/A	TXNPAD4	A3	NC	NC	
N/A	TXPPAD4	A4	NC	NC	
N/A	GNDA4	C6	NC	NC	
N/A	RXPPAD4	A5	NC	NC	
N/A	RXNPAD4	A6	NC	NC	
N/A	VTRXPAD4	B5	NC	NC	
N/A	AVCCAUXRX4	B6	NC	NC	
N/A	AVCCAUXTX6	B8			
N/A	VTTXPAD6	B7			
N/A	TXNPAD6	A7			
N/A	TXPPAD6	A8			
N/A	GNDA6	C9			
N/A	RXPPAD6	A9			
N/A	RXNPAD6	A10			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
1	IO_L54N_1		G13	NC		
1	IO_L54P_1		H13	NC		
1	IO_L53_1/No_Pair		A10	NC		
1	IO_L50_1/No_Pair		B10	NC		
1	IO_L49N_1		F14	NC		
1	IO_L49P_1		G14	NC		
1	IO_L48N_1		F12	NC		
1	IO_L48P_1		F11	NC		
1	IO_L47N_1		B9	NC		
1	IO_L47P_1		C9	NC		
1	IO_L46N_1		E13	NC		
1	IO_L46P_1		E12	NC		
1	IO_L45N_1/VREF_1		G12			
1	IO_L45P_1		H12			
1	IO_L44N_1		A8			
1	IO_L44P_1		B8			
1	IO_L43N_1		D11			
1	IO_L43P_1		E11			
1	IO_L39N_1		G11			
1	IO_L39P_1		H11			
1	IO_L38N_1		C8			
1	IO_L38P_1		D8			
1	IO_L37N_1		D10			
1	IO_L37P_1		E10			
1	IO_L09N_1/VREF_1		G10			
1	IO_L09P_1		H10			
1	IO_L08N_1		C7			
1	IO_L08P_1		D7			
1	IO_L07N_1		F10			
1	IO_L07P_1		F9			
1	IO_L06N_1		G9			
1	IO_L06P_1		H9			
1	IO_L05_1/No_Pair		G8			
1	IO_L03N_1/VREF_1		E9			
1	IO_L03P_1		E8			
1	IO_L02N_1		F8			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	VCCO_4		AA11			
4	VCCO_4		AA10			
5	VCCO_5		AB21			
5	VCCO_5		AB20			
5	VCCO_5		AB19			
5	VCCO_5		AB18			
5	VCCO_5		AA21			
5	VCCO_5		AA20			
5	VCCO_5		AA19			
5	VCCO_5		AA18			
5	VCCO_5		AA17			
5	VCCO_5		AA16			
6	VCCO_6		AB22			
6	VCCO_6		AA22			
6	VCCO_6		Y22			
6	VCCO_6		Y21			
6	VCCO_6		W22			
6	VCCO_6		W21			
6	VCCO_6		V22			
6	VCCO_6		V21			
6	VCCO_6		U21			
6	VCCO_6		T21			
7	VCCO_7		R21			
7	VCCO_7		P21			
7	VCCO_7		N22			
7	VCCO_7		N21			
7	VCCO_7		M22			
7	VCCO_7		M21			
7	VCCO_7		L22			
7	VCCO_7		L21			
7	VCCO_7		K22			
7	VCCO_7		J22			
N/A	CCLK		AC7			
N/A	PROG_B		G24			
N/A	DONE		AC8			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	GND		N17			
N/A	GND		N16			
N/A	GND		N15			
N/A	GND		N14			
N/A	GND		N13			
N/A	GND		N12			
N/A	GND		M19			
N/A	GND		M18			
N/A	GND		M17			
N/A	GND		M16			
N/A	GND		M15			
N/A	GND		M14			
N/A	GND		M13			
N/A	GND		M12			
N/A	GND		L28			
N/A	GND		L25			
N/A	GND		L20			
N/A	GND		L11			
N/A	GND		L6			
N/A	GND		L3			
N/A	GND		H30			
N/A	GND		H1			
N/A	GND		F25			
N/A	GND		F18			
N/A	GND		F13			
N/A	GND		F6			
N/A	GND		E26			
N/A	GND		E5			
N/A	GND		D27			
N/A	GND		D22			
N/A	GND		D19			
N/A	GND		D12			
N/A	GND		D9			
N/A	GND		D4			
N/A	GND		C28			
N/A	GND		C17			

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L34P_6	AE30				
6	IO_L34N_6	AE31				
6	IO_L35P_6	AD27				
6	IO_L35N_6	AD28				
6	IO_L36P_6	AF33				
6	IO_L36N_6	AE33				
6	IO_L37P_6	AD29				
6	IO_L37N_6	AD30				
6	IO_L38P_6	AB25				
6	IO_L38N_6	AB26				
6	IO_L39P_6	AD31				
6	IO_L39N_6/VREF_6	AD32				
6	IO_L40P_6	AC28				
6	IO_L40N_6	AC29				
6	IO_L41P_6	AB27				
6	IO_L41N_6	AB28				
6	IO_L42P_6	AE34				
6	IO_L42N_6	AD34				
6	IO_L43P_6	AC31				
6	IO_L43N_6	AC32				
6	IO_L44P_6	AA25				
6	IO_L44N_6	AA26				
6	IO_L45P_6	AD33				
6	IO_L45N_6/VREF_6	AC33				
6	IO_L46P_6	AB29				
6	IO_L46N_6	AB30				
6	IO_L47P_6	AA27				
6	IO_L47N_6	AA28				
6	IO_L48P_6	AB31				
6	IO_L48N_6	AB32				
6	IO_L49P_6	AA29				
6	IO_L49N_6	AA30				
6	IO_L50P_6	Y25				
6	IO_L50N_6	Y26				
6	IO_L51P_6	AC34				
6	IO_L51N_6/VREF_6	AB34				
6	IO_L52P_6	AA31				
6	IO_L52N_6	AA32				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
N/A	TXPPAD17	AP12	NC	NC	NC	
N/A	TXNPAD17	AP13	NC	NC	NC	
N/A	VTTXPAD17	AN13	NC	NC	NC	
N/A	AVCCAUXTX17	AN12	NC	NC	NC	
N/A	AVCCAUXRX18	AN14				
N/A	VTRXPAD18	AN15				
N/A	RXNPAD18	AP14				
N/A	RXPPAD18	AP15				
N/A	GNDA18	AM15				
N/A	TXPPAD18	AP16				
N/A	TXNPAD18	AP17				
N/A	VTTXPAD18	AN17				
N/A	AVCCAUXTX18	AN16				
N/A	AVCCAUXRX19	AN18				
N/A	VTRXPAD19	AN19				
N/A	RXNPAD19	AP18				
N/A	RXPPAD19	AP19				
N/A	GNDA19	AM20				
N/A	TXPPAD19	AP20				
N/A	TXNPAD19	AP21				
N/A	VTTXPAD19	AN21				
N/A	AVCCAUXTX19	AN20				
N/A	AVCCAUXRX20	AN22	NC	NC	NC	
N/A	VTRXPAD20	AN23	NC	NC	NC	
N/A	RXNPAD20	AP22	NC	NC	NC	
N/A	RXPPAD20	AP23	NC	NC	NC	
N/A	GNDA20	AM23	NC	NC	NC	
N/A	TXPPAD20	AP24	NC	NC	NC	
N/A	TXNPAD20	AP25	NC	NC	NC	
N/A	VTTXPAD20	AN25	NC	NC	NC	
N/A	AVCCAUXTX20	AN24	NC	NC	NC	
N/A	AVCCAUXRX21	AN26				
N/A	VTRXPAD21	AN27				
N/A	RXNPAD21	AP26				
N/A	RXPPAD21	AP27				
N/A	GNDA21	AM27				
N/A	TXPPAD21	AP28				
N/A	TXNPAD21	AP29				

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
1	IO_L43P_1	B13		
1	IO_L39N_1	G13		
1	IO_L39P_1	F13		
1	IO_L38N_1	J15		
1	IO_L38P_1	J14		
1	IO_L37N_1	B12		
1	IO_L37P_1	A12		
1	IO_L27N_1/VREF_1	D13		
1	IO_L27P_1	D12		
1	IO_L26N_1	L13		
1	IO_L26P_1	K13		
1	IO_L25N_1	F12		
1	IO_L25P_1	E12		
1	IO_L21N_1	B11		
1	IO_L21P_1	A11		
1	IO_L20N_1	K12		
1	IO_L20P_1	J12		
1	IO_L19N_1	C12		
1	IO_L19P_1	C11		
1	IO_L09N_1/VREF_1	F11		
1	IO_L09P_1	E11		
1	IO_L08N_1	H13		
1	IO_L08P_1	H12		
1	IO_L07N_1	G12		
1	IO_L07P_1	G11		
1	IO_L06N_1	B10		
1	IO_L06P_1	A10		
1	IO_L05_1/No_Pair	G10		
1	IO_L03N_1/VREF_1	D10		
1	IO_L03P_1	C10		
1	IO_L02N_1	K11		
1	IO_L02P_1	J11		
1	IO_L01N_1/VRP_1	F10		
1	IO_L01P_1/VRN_1	E10		
2	IO_L01N_2/VRP_2	B8		
2	IO_L01P_2/VRN_2	B9		
2	IO_L02N_2	C9		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
N/A	GND	AF30		
N/A	GND	AB30		
N/A	GND	W30		
N/A	GND	T30		
N/A	GND	N30		
N/A	GND	J30		
N/A	GND	E30		
N/A	GND	A30		
N/A	GND	AP26		
N/A	GND	AK26		
N/A	GND	AB26		
N/A	GND	W26		
N/A	GND	T26		
N/A	GND	N26		
N/A	GND	E26		
N/A	GND	A26		
N/A	GND	AE25		
N/A	GND	K25		
N/A	GND	AP22		
N/A	GND	AK22		
N/A	GND	AF22		
N/A	GND	J22		
N/A	GND	E22		
N/A	GND	A22		
N/A	GND	Y21		
N/A	GND	W21		
N/A	GND	V21		
N/A	GND	U21		
N/A	GND	T21		
N/A	GND	R21		
N/A	GND	AA20		
N/A	GND	Y20		
N/A	GND	W20		
N/A	GND	V20		
N/A	GND	U20		
N/A	GND	T20		
N/A	GND	R20		
N/A	GND	P20		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L59P_0	N21		
0	IO_L60N_0	E23		
0	IO_L60P_0	F22		
0	IO_L64N_0	D22		
0	IO_L64P_0	E22		
0	IO_L65N_0	H21		
0	IO_L65P_0	H20		
0	IO_L66N_0	G22		
0	IO_L66P_0/VREF_0	G21		
0	IO_L67N_0	D21		
0	IO_L67P_0	E21		
0	IO_L68N_0	J21		
0	IO_L68P_0	K21		
0	IO_L69N_0	C22		
0	IO_L69P_0/VREF_0	C21		
0	IO_L73N_0	F21		
0	IO_L73P_0	F20		
0	IO_L74N_0/GCLK7P	L21		
0	IO_L74P_0/GCLK6S	M21		
0	IO_L75N_0/GCLK5P	D20		
0	IO_L75P_0/GCLK4S	E20		
1	IO_L75N_1/GCLK3P	K20		
1	IO_L75P_1/GCLK2S	J20		
1	IO_L74N_1/GCLK1P	N20		
1	IO_L74P_1/GCLK0S	M20		
1	IO_L73N_1	E19		
1	IO_L73P_1	D19		
1	IO_L69N_1/VREF_1	G19		
1	IO_L69P_1	F19		
1	IO_L68N_1	L19		
1	IO_L68P_1	K19		
1	IO_L67N_1	J19		
1	IO_L67P_1	H19		
1	IO_L66N_1/VREF_1	C19		
1	IO_L66P_1	C18		
1	IO_L65N_1	N19		
1	IO_L65P_1	M19		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
0	IO_L34N_0		E30		
0	IO_L34P_0		F30		
0	IO_L35N_0		D30		
0	IO_L35P_0		C30		
0	IO_L36N_0		M28		
0	IO_L36P_0/VREF_0		M29		
0	IO_L78N_0		K29	NC	
0	IO_L78P_0		L29	NC	
0	IO_L83_0/No_Pair		H29	NC	
0	IO_L84N_0		F29	NC	
0	IO_L84P_0		G29	NC	
0	IO_L85N_0		D29	NC	
0	IO_L85P_0		E29	NC	
0	IO_L86N_0		L28	NC	
0	IO_L86P_0		K28	NC	
0	IO_L87N_0		H28	NC	
0	IO_L87P_0/VREF_0		J28	NC	
0	IO_L37N_0		E28		
0	IO_L37P_0		F28		
0	IO_L38N_0		C29		
0	IO_L38P_0		C28		
0	IO_L39N_0		L27		
0	IO_L39P_0		M27		
0	IO_L43N_0		J27		
0	IO_L43P_0		K27		
0	IO_L44N_0		H27		
0	IO_L44P_0		G27		
0	IO_L45N_0		E27		
0	IO_L45P_0/VREF_0		F27		
0	IO_L46N_0		M25		
0	IO_L46P_0		M26		
0	IO_L47N_0		L26		
0	IO_L47P_0		K26		
0	IO_L48N_0		H26		
0	IO_L48P_0		J26		
0	IO_L49N_0		F26		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L26P_7	V31	
7	IO_L26N_7	U31	
7	IO_L25P_7	L41	
7	IO_L25N_7	L42	
7	IO_L24P_7	K40	
7	IO_L24N_7	L40	
7	IO_L23P_7	T34	
7	IO_L23N_7	T35	
7	IO_L22P_7	L38	
7	IO_L22N_7/VREF_7	L39	
7	IO_L21P_7	K36	
7	IO_L21N_7	L36	
7	IO_L20P_7	T32	
7	IO_L20N_7	T33	
7	IO_L19P_7	K41	
7	IO_L19N_7	K42	
7	IO_L18P_7	K37	
7	IO_L18N_7	K38	
7	IO_L17P_7	R34	
7	IO_L17N_7	R35	
7	IO_L16P_7	H42	
7	IO_L16N_7/VREF_7	J41	
7	IO_L15P_7	J39	
7	IO_L15N_7	J40	
7	IO_L14P_7	R32	
7	IO_L14N_7	R33	
7	IO_L13P_7	J36	
7	IO_L13N_7	J37	
7	IO_L12P_7	H40	
7	IO_L12N_7	H41	
7	IO_L11P_7	T31	
7	IO_L11N_7	R31	
7	IO_L10P_7	H38	
7	IO_L10N_7/VREF_7	H39	
7	IO_L09P_7	H36	
7	IO_L09N_7	H37	
7	IO_L08P_7	P34	

Date	Version	Revision
11/17/04	4.1	• Table 4: Added requirement to V_{BATT} to connect pin to V_{CCAUX} or GND if battery is not used.
03/01/05	4.2	• Table 3: Corrected number of Differential I/O Pairs for XC2VP30-FF1152 from 340 to 316. • Table 4: Changed Direction for User I/O pins (IO_LXXY_#) from “Input/Output” to “Input/Output/Bidirectional”.
06/20/05	4.3	*No changes in Module 4 for this revision.*
09/15/05	4.4	*No changes in Module 4 for this revision.*
10/10/05	4.5	*No changes in Module 4 for this revision.*
03/05/07	4.6	• Figure 2, page 29: Corrected NOTE 3. • Figure 7, page 161: Updated with drawing showing correct heat sink profile and detail.
11/05/07	4.7	Updated copyright notice and legal disclaimer.
06/21/11	5.0	Added *Product Not Recommended for New Designs* banner. Updated Figure 3, page 50, with the newest FG676/FGG676 mechanical drawing.

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Virtex-II Pro Data Sheet

The Virtex-II Pro Data Sheet contains the following modules:

- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview (Module 1)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description (Module 2)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics (Module 3)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information (Module 4)